TMG160N10HT

N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

General Features

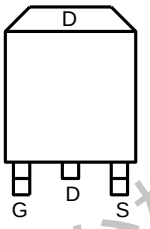
V_{DS} = 100V I_D = 160A

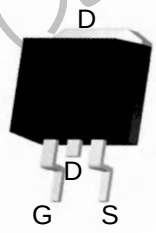
$R_{DS(ON)}$ =3.3mΩ (typ.) @ V_{GS}=10V

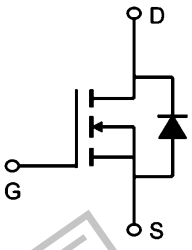
100% UIS Tested

100% R_g Tested

T:TO-263-3L







Marking: G160N10

Absolute Maximum Ratings (T_C = 25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25°C	Continuous Drain Current, V_{GS} @ 10V[1]	160	A
I_D@T_C=100°C	Continuous Drain Current, V_{GS} @ 10V[1]	96	A
I_{DM}	Pulsed Drain Current[2]	619	A
EAS	Single Pulse Avalanche Energy[3]	726	mJ
I_{AS}	Avalanche Current	150	A
P_D@T_C=25°C	Total Power Dissipation[3]	312	W
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient [1]	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	6.6	°C/W

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Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	100	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	---	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=20A	---	3.3	3.8	mΩ
		V_{GS}=4.5V , I_D=10A	---	---	---	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	2.0	3.0	4.0	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=80V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=80V, V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=20A	---	50	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.9	---	Ω
Q_g	Total Gate Charge	V_{DS}=50V , V_{GS}=10V , I_D=20A	---	84	---	nC
Q_{gs}	Gate-Source Charge		---	24	---	
Q_{gd}	Gate-Drain Charge		---	27	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=50V , V_{GS}=10V , R_G=2.5Ω, I_D=10A	---	21	---	ns
T_r	Rise Time		---	35	---	
$T_{d(off)}$	Turn-Off Delay Time		---	49	---	
T_f	Fall Time		---	30	---	
C_{iss}	Input Capacitance	V_{DS}=50V , V_{GS}=0V , f=1MHz	---	4797	---	pF
C_{oss}	Output Capacitance		---	900	---	
C_{rss}	Reverse Transfer Capacitance		---	19.1	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	160	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.2	V

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is TJ = 25°C, L = 3mH, IAS = 22A, VGS = 10V, VDD = 50V; 100% test at L = 0.3mH, IAS = 45A.
4.The power dissipation is limited by 150℃ junction temperature
5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

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Typical Electrical & Thermal Characteristics

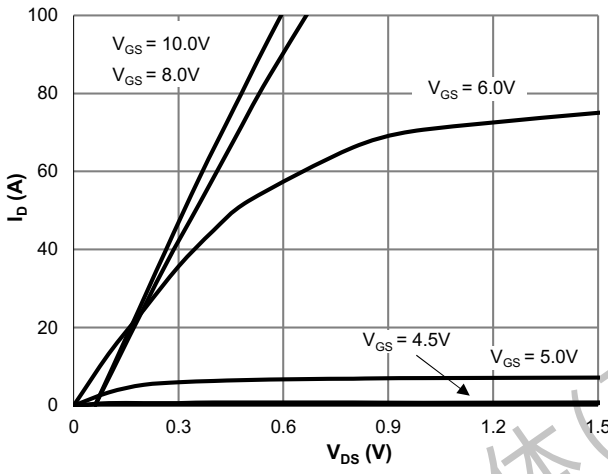

Figure 1: Saturation Characteristics

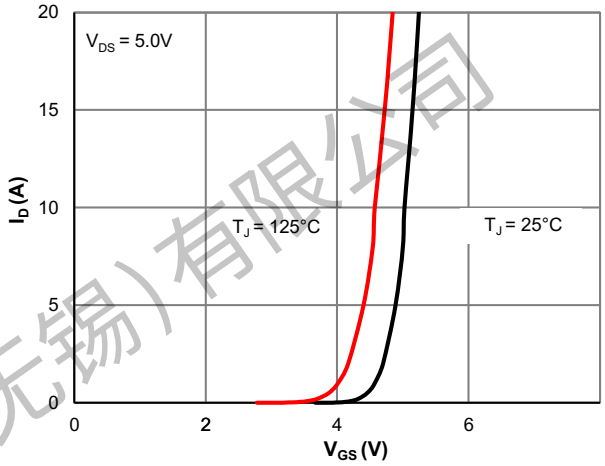

Figure 2: Transfer Characteristics

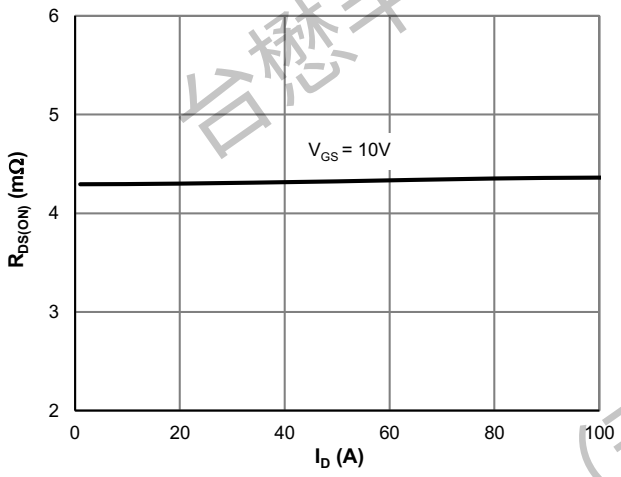

Figure 3: $R_{DS(ON)}$ vs. Drain Current

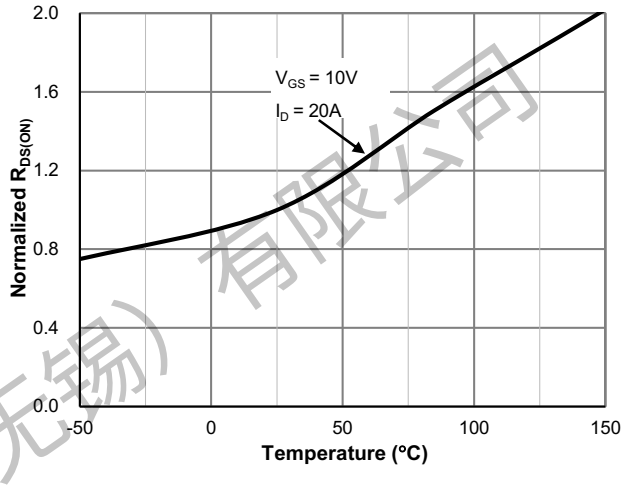

Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

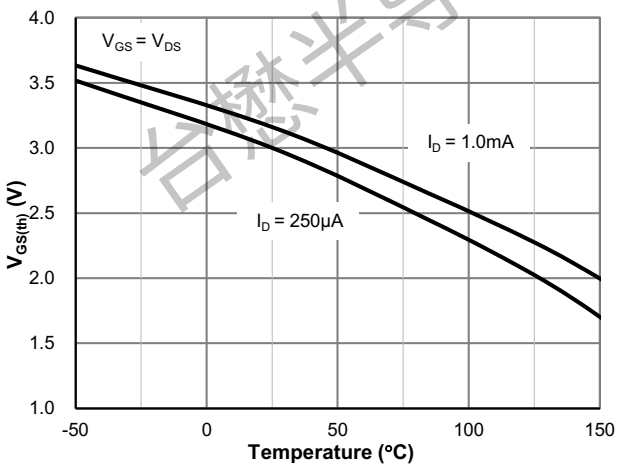

Figure 5: $V_{GS(th)}$ vs. Junction Temperature

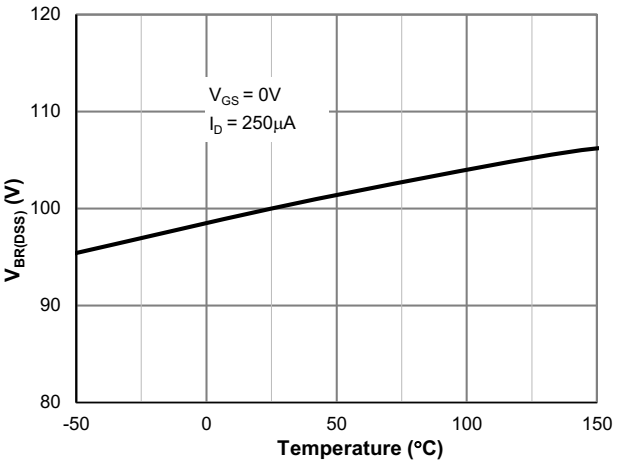

Figure 6: $V_{BR(DSS)}$ vs. Junction Temperature

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Typical Electrical & Thermal Characteristics

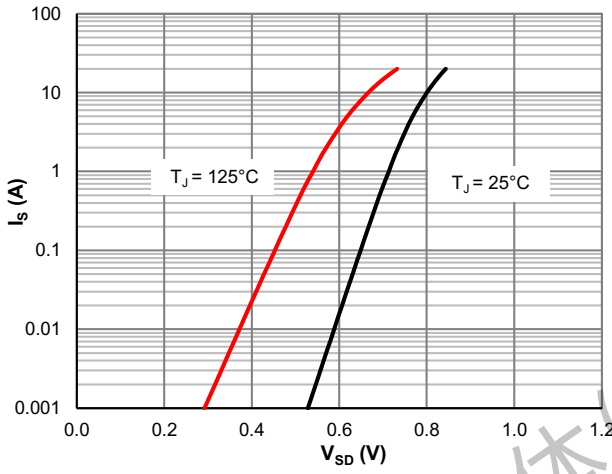

Figure 7: Body-Diode Characteristics

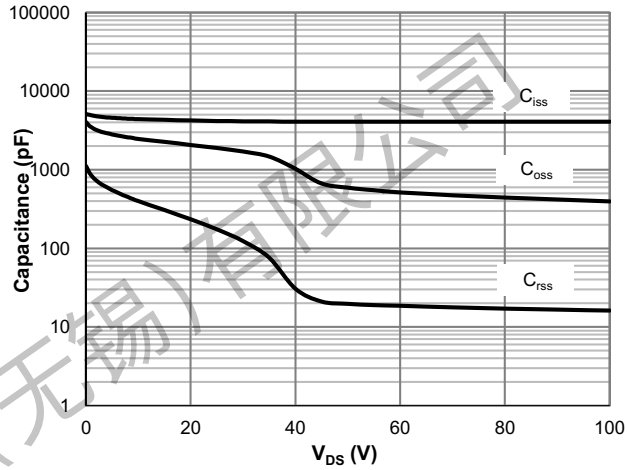

Figure 8: Capacitance Characteristics

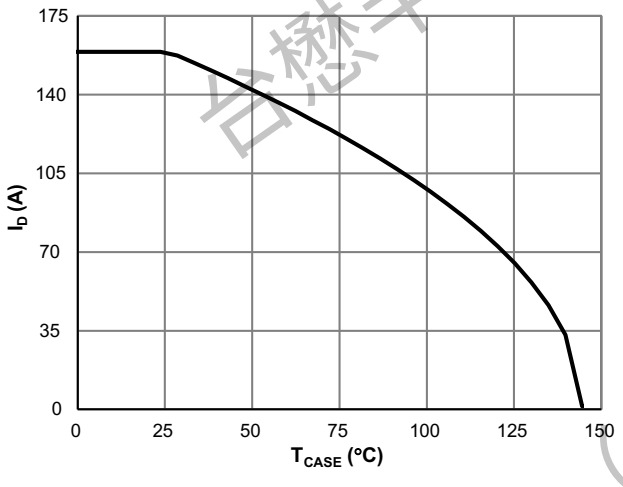

Figure 9: Current De-rating

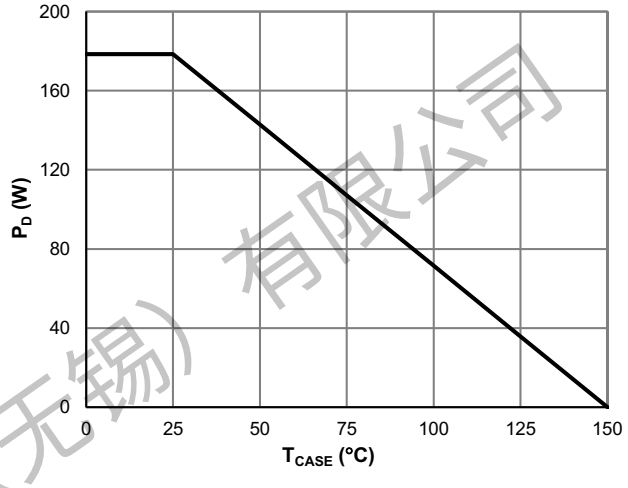

Figure 10: Power De-rating

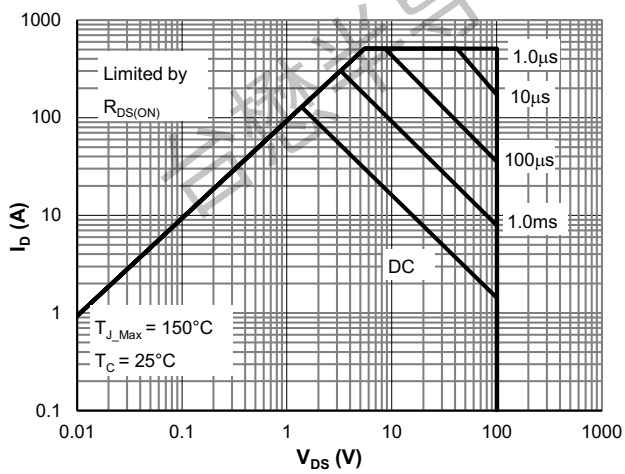

Figure 11: Maximum Safe Operating Area

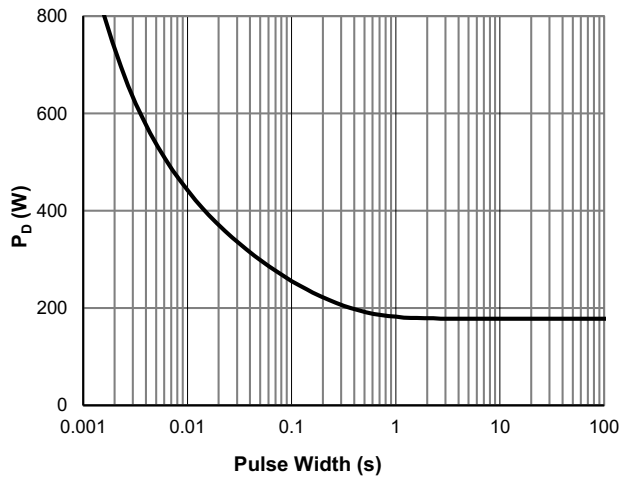

Figure 12: Single Pulse Power Rating, Junction-to-Case

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Typical Electrical & Thermal Characteristics

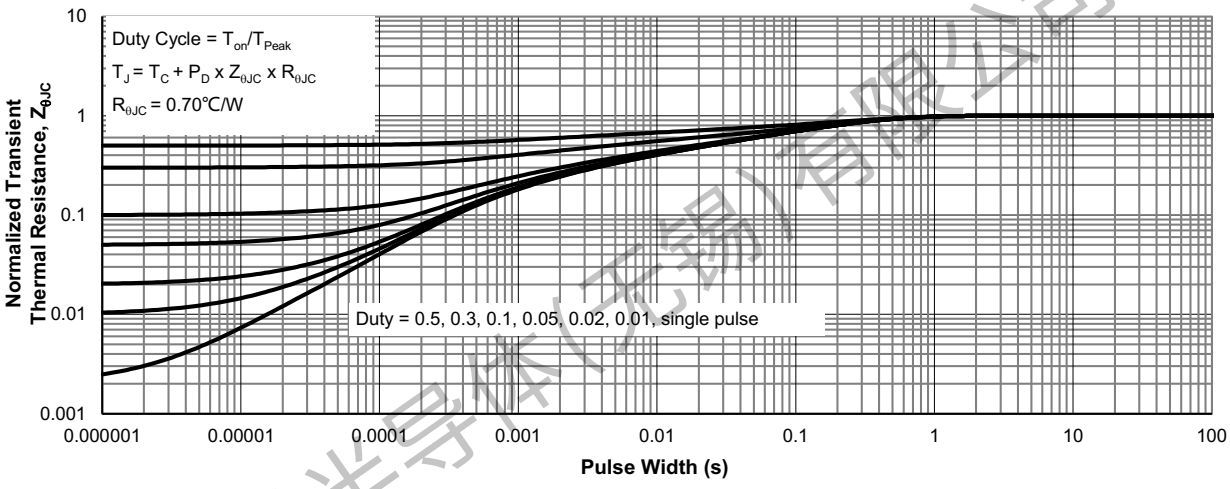

Figure 13: Normalized Maximum Transient Thermal Impedance

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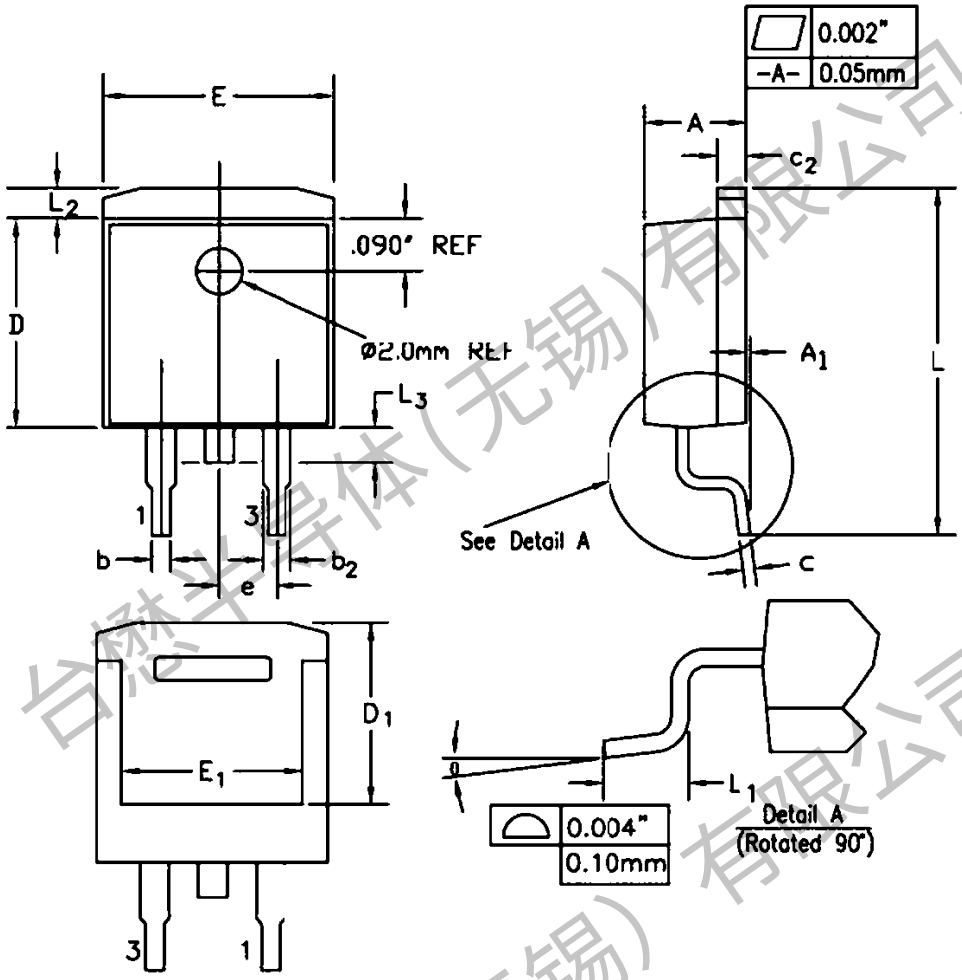
Package Mechanical Data: TO-263-3L



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	
A1	-	0.010	-	0.25	
b	0.028	0.037	0.71	0.94	
b2	0.045	0.055	1.15	1.40	
c	0.018	0.024	0.46	0.61	
c2	0.048	0.055	1.22	1.40	
D	0.350	0.370	8.89	9.40	
D1	0.315	0.324	8.01	8.23	
E	0.395	0.405	10.04	10.28	
E1	0.310	0.318	7.88	8.08	
e	0.100 BSC.		2.54 BSC.		
L	0.580	0.620	14.73	15.75	
L1	0.090	0.110	2.29	2.79	
L2	0.045	0.055	1.15	1.39	
L3	0.050	0.070	1.27	1.77	
θ	0°	8°	0°	8°	

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Revision history:

Date	Rev	Description	Page
2023.05.31	23.05	Original	

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